
Actions

MICROELECTRONICS Co., Ltd.

Actions-micro AM8269D Datasheet

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Revision History

| Version | Date | Description | Author |
|---------|------------|----------------|-----------|
| 1.0 | 12/24/2018 | Initial Create | maweishuo |

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Terms and Acronyms

| Terms and Acronyms | Definition |
|--------------------|--|
| CF | Compact Flash |
| SM | Smart Media |
| XD | xD picture |
| SD | Secure Digital |
| Micro SD | Micro Secure Digital |
| MS | Memory Stick |
| MS Pro | Memory Stick Pro |
| MMC | Multimedia Card |
| SDRAM | Synchronous Dynamic Random Access Memory |
| MD | MicroDrive |
| TF | T Flash |
| LCD | Liquid Crystal Display |
| ICE | In-circuit emulation, or in-circuit emulator |
| JTAG | Joint Test Action Group(ANSI/ICEEE Std.11149.1-1990) |
| PQFP | Plastic Quad Flat Package |
| LQFP | Low-Profile Quad Flat Package |
| BGA | Ball Grid Array |
| PIP | Picture In Picture |
| TAP | TEST ACCESS PORT |
| RGB | Red-Green-Blue color space representation |
| TCON | Timing controller |
| | |
| | |

General Conventions

| Symbol | Description | Notes |
|-------------------------------------|--|-------|
| Note | | |
| H | In the notes column, an H indicates the pin is hidden behind the actual physical pin listed in the Alternate Functions column and is not included in the pin count. No H indicates the actual pin is listed in the Signal Name column and the Alternate Functions column lists the alternate signals present on the pin. | |
| Pad GP | | |
| 1 | Pad group 1 | |
| 2 | Pad group 2 | |
| Dir/Pol (direction/polarity) | | |
| I | Input | |
| O | Output | |
| B | Bidirectional | |
| Z | Three state output | |
| Pad Type | | |
| A | Analog pad | |
| B | Bidirectional | |
| BS | Bidirectional with Schmitt trigger | |
| H | High-voltage(up to 3.0 V)tolerant digital input | |
| I | CMOS input | |
| IA | Analog input | |
| IS | Input with Schmitt trigger | |
| K | Contains an internal weak keeper device | |
| O | Output | |
| OA | Analog output | |
| OD | Open-drain | |
| PD | Contains an internal pull-down device | |
| PP[NP] | Can be programmed to non pull, pull down or pull up. The default value is no pull after reset. | |
| PP[PD] | Can be programmed to non pull, pull down or pull up. The default value is pull down after reset. | |
| PP[PU] | Can be programmed to non pull, pull down or pull up. The default value is pull up after reset. | |
| PU | Contains an internal pull-up device | |
| PWR | power | |
| Z | High-Z output | |
| Drive (mA) | | |
| n | Variable drive strength pins. | |

1 Introduction

1.1 Overview

The AM8269D processor from Actions-Micro is a highly integrated mix signal SoC target at multi-media applications. The AM8269D emmedded CPU is a high performance, low power 32bit RISC core with DSP instruction extension, which can run as fast as 800MHz.

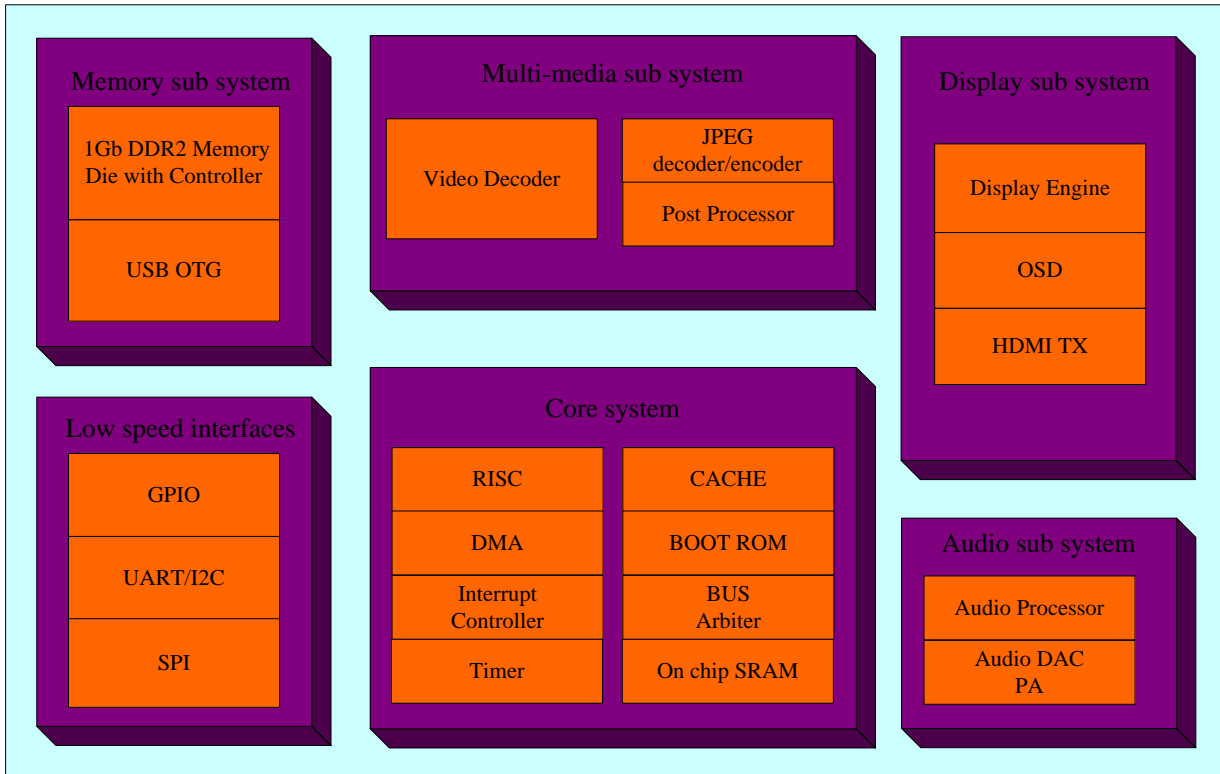
The AM8269D processor features a hardwired multi-format video decoder, which supports a large variety of popular video formats including: H.264, RMVB, MPEG1/2/4 and VC1 at full HD resolution. The AM8269D integrated image/video post processor and display engine provide a powerful image processing ability, such as seamless zoom in/zoom out, cropping, rotation, color space conversion, gamma correction, edge enhancement, dithering, brightness, contrast and saturation adjustment. Moreover, a configurable FIR is reserved for other special effects extension. The 2 layers of OSD window can be configured as large as full screen and the color depth is ranging from 1 bit to 32bit true color.

The AM8269D multi-media processor provided display solutions: with the help of on chip HDMI.

AM8269D is also integrated with 1 USB OTG controllers, UART, I2C, SPI,etc.

There is a 1Gb DDR2 memory die integrated in AM8269D, so no need to hang a DDR2 memory on PCB.

1.2 Block Diagram



AM8269D BLOCK DIAGRAM

2 Feature

The AM8269D provides high level of system integration to support a wide variety of applications. The features of the AM8269D include:

✓ **32BIT RISC CORE**

- 32K byte instruction cache and data cache
- F/W can program from DC up to 800MHz transparently
- DSP instruction for multi-media acceleration
- Static design allows changing clock at run-time for power saving

✓ **VIDEO DECODER**

- Multi-format supported including:

| | |
|---------------------------------|---|
| H.264 profile and level | Up to High Profile ,levels 1-4.1 |
| MPEG-4 visual profile and level | Advanced Simple profile(frame picture) , levels 0-5 |
| H.263 profile and level | Profile 0, levels 10-70. Image size up to 720x576, time code extensions not supported |
| VC-1 profile and level | Simple and Main profile; low, medium and high levels |
| MPEG-2/MPEG-1 | Main profile; low and main levels, MPEG-1 D-picture not support |
| RV8/9/10 | |

- 30 frames per second at 1920x1080 resolution for all format
- Adaptive De-interlacing

✓ **JPEG DECODER**

- Support JPEG baseline
- Support YCbCr 4:2:0 planar and semiplanar
- Support YCbYCr & CbYCrY 4:2:2 interleaved
- Support image size: from 80x16 to 4672x3504
- Support rotate: +90° , -90°

✓ **IMAGE/VIDEO POST PROCESSOR**

- Image up/down scaling at arbitrary non-integer scaling ratio
- Separate scaling ratio for horizontal and vertical dimensions
- Image cropping
- Image crossing

- Image rotation, 90 180 and 270 degrees and horizontal/vertical flip
 - Image mask, output image writing can be prevented on two rectangular areas
 - Support YUV444/YUV422/RGB888/RGB565 for mask window for alpha blending(256 level)
 - YUV/RGB conversion
 - Maximum output image size up to 1920x1080
- ✓ **Display Engine**
- YCbCr/RGB conversion, user definable conversion coefficients
 - Image up scaling at arbitrary non-integer scaling ratio
 - Separate scaling ratio for horizontal and vertical dimensions
 - brightness, contrast and saturation adjust
 - Edge enhancement
 - Dynamic contrast adjust
 - Direct mapped Gamma correction for RGB channel separately
 - 24bit to 16/18 bit Bayer pattern/1D/2D method dithering
 - Support progressive and interlace input format
 - Support YUV4:2:2(interleave), YUV4:2:0(semi planar), RGB565, RGB888 input forma
 - 16x16 hardware cursor
- ✓ **OSD**
- Two layers of OSD window with overlap
 - 8 level alpha blending for each window
 - 1,2,4 or 8 bits OSD bitmap data width
 - Transparency pixels allowed in OSD window
 - Two configurable OSD palettes
 - Each one of the 2 OSD windows can fetch RGB565/ARGB8888 data from system memory directly
- ✓ **DISPLAY INTERFACE**
- HDMI Tx support, industry standard compliance HDMI 1.2
 - Support output size up to 1920x1080
 - Configurable horizontal sync interrupt
- ✓ **AUDIO**
- Multi-format audio decoder:MP1/MP2/MP3/WMA/AAC/AMR-NB/WAV/PCM/ADPCM
 - Build in Stereo 18-bit Sigma-Delta DAC: SNR>92db(no a-weight), 18bits,sample rate 8/12/11.05/16/22/24/32/44.1/48
 - Support 32 levels volume control

- ✓ **MEMORY Storage**
 - Integrated with a 1Gb DDR2 die which is up to 1066Mbps
 - OTP ROM 64bit Chip ID

- ✓ **DMA CONTROLLER**
 - 8 physical channels and 4 bus channels
 - Stride mode support
 - Software configurable priority

- ✓ **Boot ROM**
 - On chip boot ROM with boot loader
 - The system could be loaded from SPI Nor flash

- ✓ **USB 2.0 OTG**
 - Complies with Universal Serial Bus Specification. Revision 2.0.
 - Complies with On-The-Go Supplement to the USB2.0 Specification Revision 1.0a.
 - Supports point-to-point communication with one low-speed, full-speed or high-speed device in Host mode.
 - Supports full-speed or high-speed in peripheral mode.
 - Supports USB Mass Storage Class Bulk-Only Transport Revision 1.0 as host or device.
 - Supports Electronic still picture imaging Picture Transfer Protocol (PTP)
 - Supports direct print function using pict-bridge
 - Supports Universal Serial Bus Device Class Definition for Printing Devices Version 1.1 as host
 - Supports Universal Serial Bus Still Image Capture Device Definition Revision 1.0 as host
 - Configurable/programmable size of endpoints.
 - Configurable/programmable single, double, triple or quad buffering.
 - Programmable type of endpoints.
 - Supports high-speed high-bandwidth Isochronous and Interrupt transfer.
 - Supports suspend, resume and power managements function.
 - Support USB wakeup

- ✓ **OTHER INTERFACE**
 - UART/I2C/SPI
 - 3 external interrupts
 - 41 configurable GPIO shared with function pins

- ✓ **POWER**
 - 1.3v for core

- 3.3v/2.5v/1.5v for IO
- Build in 1.5v bandgap reference
- Core PLL, LCD PLL, Audio PLL and DDR PLL support spread spectrum

✓ **PACKAGE**

- QFN 68(epad)

ACTIONS-MICRO

3 Power on Sequence

The power on sequence requirements of the AM7xxx and AM8xxx products are the same, which are shown in the following figure. VDD represents the power pins supplying power for the core. VCC represents the power pins supplying power for the general purpose pads. SVCC represents the power pins supplying power for the DDR2 or DDR3 SDRAM related pads. P_RESETB is the asynchronous reset pin. PWROK is an internal signal. It is low during the power-on phase to reset all the registers in the chip. The system boots at the moment when PWROK turns to high.

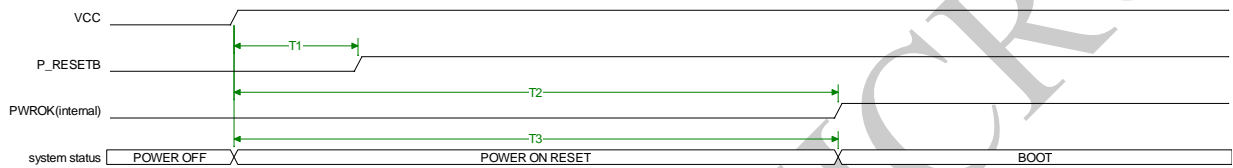


Figure 1 Power on Sequence Diagram

Timing Requirements:

1. $T1 \geq 20ms$
2. $T2 \approx 128ms$
3. $T3$ is equal to the greater one between $T1$ and $T2$
4. The power on sequence of VDD/VCC/SVCC is not cared

4 Registers

| Module name | Physical Bass Address | KSEG1 Base Adress |
|-------------|-----------------------|-------------------|
| MFP | 0x101C0000 | 0xB01C0000 |

4.1 Multi-Function PAD Config Registers

4.1.1 MFP Configuration Register-0

Offset=0x0040

| Bit | Name | Descriptions | | | | | | default |
|-----------------|---------------|--------------|---------------------|--------|--------|-----------|-------|---------|
| | | Bit Value | Function | PU/PD | In/Out | Default I | HI/LO | |
| mfp0[0] | - | - | Reserved | | | | | 0 |
| mfp0[1] | P_I2CSCL | 0 | GPIO[1] | | B | | | 0 |
| | | 1 | I2C0_SCL | PU2.2K | 1/O | 1 | LOW | 0 |
| mfp0[2] | P_I2CSDA | 0 | GPIO[2] | | B | | | 0 |
| | | 1 | I2C0_SDA | PU2.2K | 1/O | 1 | LOW | 0 |
| mfp0[3] | P_GPIO0 | 0 | SD_D0 | | B | | | 0 |
| | | 1 | PWM0 | | 0/1 | | | 0 |
| mfp0[4] | P_GPIO1 | 0 | SD_D1 | | B | | | 0 |
| | | 1 | PWM1 | | 0/1 | | | 0 |
| mfp0[5] | P_GPIO2 | 0 | BOOT_SEL 0 | | 1/0 | | | 0 |
| | | 1 | SD_D2 | | B | | | 0 |
| mfp0[6] | P_GPIO3 | 0 | BOOT_SEL 1 | | 1/0 | | | 0 |
| | | 1 | SD_D3 | | B | | | 0 |
| mfp0[7] | P_GPIO4 | 0 | SD_CLK | | B | | | 0 |
| | | 1 | I2C1_SCL | PU2.2K | 1/O | 1 | LOW | 0 |
| mfp0[8] | P_GPIO5 | 0 | SD_CMD | | B | | | 0 |
| | | 1 | I2C1_SDA | PU2.2K | 1/O | 1 | LOW | 0 |
| mfp0[10:9] | P_DRVVB US | 0 | EJ_DINT | PD100K | 1/0 | | | 0 |
| | | 1 | DRVVBUS | | 0/1 | | | 0 |
| | | 10 | GPIO[9] | | B | | | 0 |
| mfp0[12:1 1] | P_EXTINT 0 | 0 | GPIO[10] | | B | | | 0 |
| | | 1 | EXT_INT[0] | | 1/0 | lowact | SP | 0 |
| | | 10 | HDMI_HO TPLUG_IN | | 1/0 | | | 0 |

| | | | | | | | | |
|-------------|---------------|----|------------|--------|-----|--------|-----|---|
| mfp0[14:13] | P_EXTINT 1 | 0 | EJ_TCK | PU100K | 1/0 | 1 | LOW | 0 |
| | | 1 | GPIO[11] | | B | | | 0 |
| | | 10 | EXT_INT[1] | PU100K | 1/0 | lowact | SP | 0 |
| mfp0[15] | P_EXTINT 2 | 0 | GPIO[12] | | B | | | 0 |
| | | 1 | EXT_INT[2] | PU100K | 1/0 | lowact | SP | 0 |
| mfp0[16] | P_UARTTX | 0 | GPIO[13] | | B | | | 0 |
| | | 1 | UART_TX | | 0/1 | | | 0 |
| mfp0[18:17] | P_UARTR X | 0 | EJ_TDO | | O | | | 0 |
| | | 1 | UART_RX | | 1/0 | 1 | LOW | 0 |
| | | 10 | GPIO[14] | | B | | | 0 |
| mfp0[19] | P_TEST | 0 | (TEST) | PD100K | 1/0 | | | 0 |
| | | 1 | GPIO[15] | | O | | | 0 |
| mfp0[20] | P_SPICLK | 0 | GPIO[16] | | B | | | 0 |
| | | 1 | SPI_CLK | | 1/O | | | 0 |
| mfp0[21] | P_SPIMOSI | 0 | GPIO[17] | | B | | | 0 |
| | | 1 | SPI_MOSI | | 1/O | | | 0 |
| mfp0[22] | P_SPIMISO | 0 | GPIO[18] | | B | | | 0 |
| | | 1 | SPI_MISO | | 1/0 | | | 0 |
| mfp0[24:23] | P_SPIHOL D | 0 | EJ_TMS | PU100K | 1/0 | 1 | LOW | 0 |
| | | 1 | SPI_HOLD | | 1/O | | | 0 |
| | | 10 | GPIO[19] | | B | | | 0 |
| mfp0[26:25] | P_SPIWP | 0 | EJ_TRST_ | | 1/0 | 1 | LOW | 0 |
| | | 1 | SPI_WP | | 1/O | | | 0 |
| | | 10 | GPIO[20] | | B | | | 0 |
| mfp0[28:27] | P_SPINSS | 0 | EJ_TDI | PU100K | 1/0 | 1 | LOW | 0 |
| | | 1 | GPIO[21] | | B | | | 0 |
| | | 10 | SPI_NSS | | 1/O | 1 | LOW | 0 |
| mfp0[29] | P_SPINSS2 | 0 | GPIO[22] | | O | | | 0 |

5 Pin Out Specification

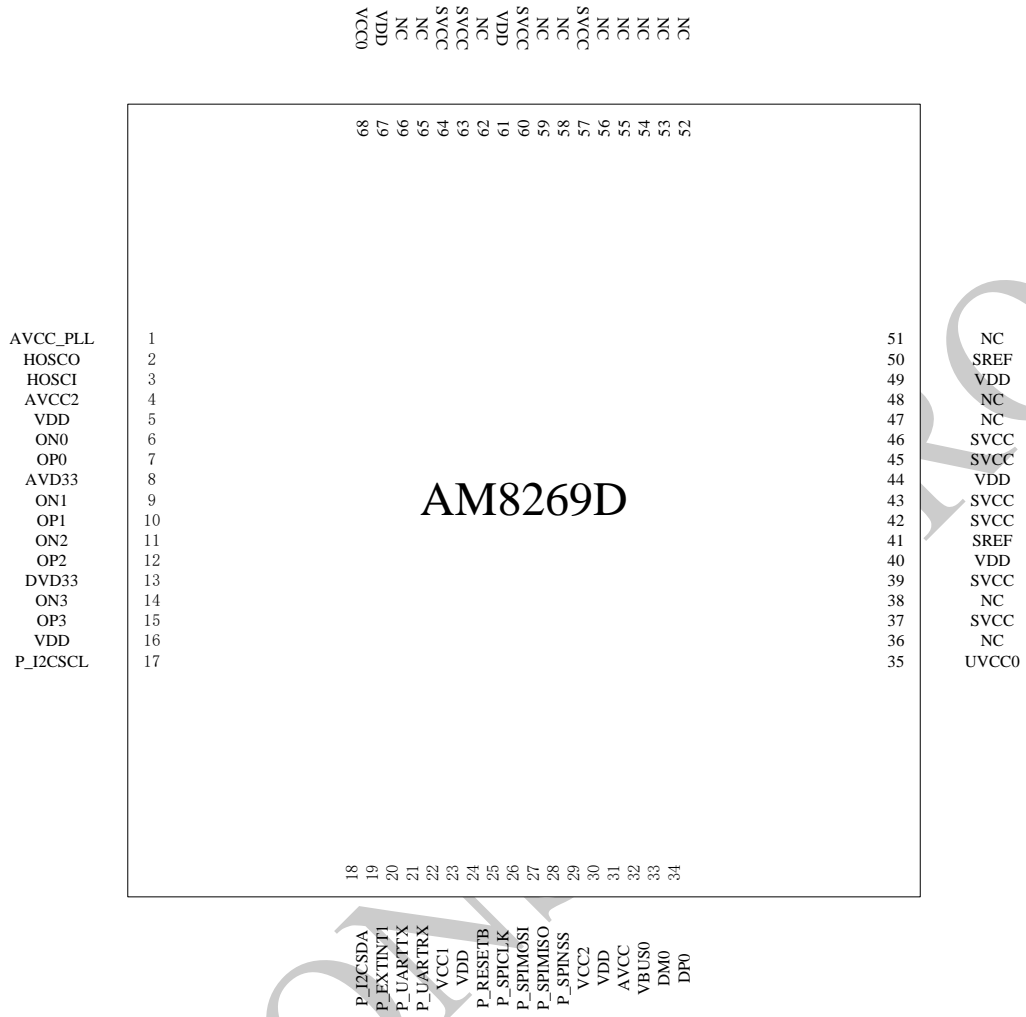
5.1 Pin out table

| PINNUM | PIN NAME | TYPE | PIN Function |
|--------|----------|------|--------------|
| 1 | AVCC_PLL | PWR | AVCC_PLL |
| 2 | HOSCO | A | HOSCO |
| 3 | HOSCI | A | HOSCI |

| | | | |
|----|-----------|-----|---------|
| 4 | AVCC2 | PWR | AVCC2 |
| 5 | VDD | PWR | VDD |
| 6 | ON0 | A | HDMI |
| 7 | OP0 | A | HDMI |
| 8 | AVD33 | PWR | HDMI |
| 9 | ON1 | A | HDMI |
| 10 | OP1 | A | HDMI |
| 11 | ON2 | A | HDMI |
| 12 | OP2 | A | HDMI |
| 13 | DVD33 | PWR | HDMI |
| 14 | ON3 | A | HDMI |
| 15 | OP3 | A | HDMI |
| 16 | VDD | PWR | VDD |
| 17 | P_I2CSCL | B | I2CSCL |
| 18 | P_I2CSDA | B | I2CSDA |
| 19 | P_EXTINT1 | B | EXTINT1 |
| 20 | P_UARTTX | B | UARTTX |
| 21 | P_UARTRX | B | UARTRX |
| 22 | VCC1 | PWR | VCC |
| 23 | VDD | PWR | VDD |
| 24 | P_RESETB | I | RESETB |
| 25 | P_SPICLK | B | SPICLK |
| 26 | P_SPIMOSI | B | SPIMOSI |
| 27 | P_SPIMISO | B | SPIMISO |
| 28 | P_SPINSS | B | SPINSS |
| 29 | VCC2 | PWR | VCC2 |
| 30 | VDD | PWR | VDD |
| 31 | AVCC | PWR | AVCC |
| 32 | VBUS0 | A | VBUS0 |
| 33 | DM0 | A | DM0 |
| 34 | DP0 | A | DP0 |
| 35 | UVCC0 | PWR | UVCC0 |
| 36 | NC | - | - |
| 37 | SVCC | PWR | SVCC |
| 38 | NC | - | - |
| 39 | SVCC | PWR | SVCC |
| 40 | VDD | PWR | VDD |
| 41 | SREF | PWR | SREF |
| 42 | SVCC | PWR | SVCC |
| 43 | SVCC | PWR | SVCC |
| 44 | VDD | PWR | VDD |
| 45 | SVCC | PWR | SVCC |

| | | | |
|----|------|-----|------|
| 46 | SVCC | PWR | SVCC |
| 47 | - | - | - |
| 48 | - | - | - |
| 49 | VDD | PWR | VDD |
| 50 | SREF | PWR | SREF |
| 51 | NC | - | - |
| 52 | NC | - | - |
| 53 | NC | - | - |
| 54 | NC | - | - |
| 55 | NC | - | - |
| 56 | NC | - | - |
| 57 | SVCC | PWR | SVCC |
| 58 | NC | - | - |
| 59 | NC | - | - |
| 60 | SVCC | PWR | SVCC |
| 61 | VDD | PWR | VDD |
| 62 | NC | - | - |
| 63 | SVCC | PWR | SVCC |
| 64 | SVCC | PWR | SVCC |
| 65 | NC | - | - |
| 66 | NC | - | - |
| 67 | VDD | PWR | VDD |
| 68 | VCC0 | PWR | VCC0 |

5.2 Pin out diagram



AM8269D PIN-OUT DIAGRAM

6 Operating Conditions

Absolute Maximum Ratings

| SYMBOL | PARAMETER | RATING | UNITS |
|-------------------|---|----------|-------|
| V _{cc} | Power Supply (3.3V) | 3.8 | V |
| V _{svcc} | Power Supply (1.5V) | 1.575 | V |
| V _{dd} | Power Supply (1.35V) | 1.4 | V |
| V _{IN} | Input Voltage | -0.5~4.6 | V |
| V _{OUT} | Output Voltage | -0.5~4.6 | V |
| T _{STG} | Storage Temperature | 0~75 | °C |
| T _c | Operation Temperature (Case Surface) | 0~90 | °C |
| T _a | Ambient Temperature | 0~60 | °C |

Recommended Operation Conditions

| SYMBOL | PARAMETER | MIN | TYP | MAX | UNITS |
|-------------------|----------------------|-------|------|-------|-------|
| V _{cc} | Power Supply (3.3V) | 3.0 | 3.3 | 3.6 | V |
| V _{svcc} | Power Supply (1.5V) | 1.425 | 1.5 | 1.575 | V |
| V _{dd} | Power Supply (1.35V) | 1.3 | 1.35 | 1.4 | V |
| T _a | Ambient Temperature | 0 | 35 | 60 | °C |

DC Electrical Characteristics for 3.3 volts operation

(Under Recommended Operating Conditions and V_{cc} = 3.0V~3.6V, T_j = 0 to +70) °C °C

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX | UNITS |
|-----------------|----------------------------|------------|-----|-----|-----|-------|
| V _{IL} | Input Low Voltage | | | | 0.8 | V |
| V _{IH} | Input High Voltage | | 2.2 | | | V |
| V _{T-} | Schmitt Input Low Voltage | | | | 0.9 | V |
| V _{T+} | Schmitt Input High Voltage | | 1.9 | | | V |
| V _{OL} | Output Low Voltage | 4mA | | | 0.4 | V |
| V _{OH} | Output High Voltage | 4mA | 2.4 | | | V |

7 Crystal Requirements

Requirements for 24MHz oscillator.

| Description | Specification Requirement |
|------------------------------------|--------------------------------------|
| Nominal Frequency | 24MHz |
| Oscillation Mode | Fundamental |
| Frequency Tolerance at 25°C | ±30ppm |
| Temperature Stability | ±50ppm |
| Shunt Capacitance (Co) | 7pF (max) |
| Load Capacitance (CL) | 12pF~18pF |
| Equivalent Series Resistance (ESR) | 50ohm (max) |
| Drive Level | 500uW (max) |
| Aging (at 25°C) | ±3ppm/year |
| Insulation Resistance | 10meg |
| Net Weight | This will be various. No limitation. |
| Operating Temperature Range | -10~90°C |
| Storage Temperature Range | -45~125°C |

Requirements for 32.768KHz oscillator.

| Description | Specification Requirement |
|------------------------------------|--------------------------------------|
| Nominal Frequency | 32.768KHz |
| Oscillation Mode | Fundamental |
| Frequency Tolerance at 25°C | ±30ppm |
| Temperature Stability | ±50ppm |
| Shunt Capacitance (Co) | 7pF (max) |
| Load Capacitance (CL) | 12pF~18pF |
| Equivalent Series Resistance (ESR) | 50ohm (max) |
| Drive Level | 500uW (max) |
| Aging (at 25°C) | ±3ppm/year |
| Insulation Resistance | 10meg |
| Net Weight | This will be various. No limitation. |
| Operating Temperature Range | -10~90°C |
| Storage Temperature Range | -45~125°C |

8 Mechanical Specification

